

L Number	Hits	Search Text	DB	Time stamp
1	5258	"inductive couple plasma" or ICP	USPAT; EPO; JPO; IBM_TDB	2003/04/03 08:32
2	29	(AlCu or "copper-aluminum") and (BCl3 or "boron thichloride" or "BCl.sub.3" or chlorine or "Cl.sub.2") and volume and pressure and "flow rate"	USPAT; EPO; JPO; IBM_TDB	2003/04/03 11:00
3	50	(AlCu or "copper-aluminum") same (BCl3 or "boron thichloride" or "BCl.sub.3" or chlorine or "Cl.sub.2") same etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/04/03 09:36
7	396	(gas adj time) and etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/04/03 09:41
8	14	("inductive couple plasma" or ICP) and ((gas adj time) and etch\$3)	USPAT; EPO; JPO; IBM_TDB	2003/04/03 09:39
9	9178	etch\$3 and volume and pressure and "flow rate"	USPAT; EPO; JPO; IBM_TDB	2003/04/03 09:44
10	194	etch\$3 same volume same pressure same "flow rate"	USPAT; EPO; JPO; IBM_TDB	2003/04/03 10:32
11	14	"etching time" and (chamber adj volume) and pressure and "flow rate"	USPAT; EPO; JPO; IBM_TDB	2003/04/03 10:33
12	58	(AlCu or "copper-aluminum") same (BCl3 or "boron thichloride" or "BCl.sub.3" or chlorine or "Cl.sub.2")	USPAT; EPO; JPO; IBM_TDB	2003/04/03 10:59
14	281	(AlCu or "copper-aluminum") and (BCl3 or "boron thichloride" or "BCl.sub.3" or chlorine or "Cl.sub.2")	USPAT; EPO; JPO; IBM_TDB	2003/04/03 11:00
16	127	((AlCu or "copper-aluminum") and (BCl3 or "boron thichloride" or "BCl.sub.3" or chlorine or "Cl.sub.2")) and 438/\$.ccls.	USPAT; EPO; JPO; IBM_TDB	2003/04/03 11:01
17	2093	((438/706) or (438/710) or (438/712) or (438/720)).CCLS.	USPAT; EPO; JPO; IBM_TDB	2003/04/03 11:01
18	27	((AlCu or "copper-aluminum") and (BCl3 or "boron thichloride" or "BCl.sub.3" or chlorine or "Cl.sub.2")) and (((438/706) or (438/710) or (438/712) or (438/720)).CCLS.)	USPAT; EPO; JPO; IBM_TDB	2003/04/03 11:01